

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-5 (canceled).

Claim 6 (previously presented): An electronic component device comprising:
a rectangular plate-shaped element including a functional part and a first frame-shaped electrode surrounding the functional part, wherein the coefficient of linear expansion in the x direction along a side of the rectangle is different from the coefficient of linear expansion in the y direction orthogonal to the x direction in the rectangular plane;

a substrate including a second frame-shaped electrode arranged on a front face of the substrate at a position so as to correspond to the first frame-shaped electrode;
and

a solder sealing frame provided on the surface of at least one of the first frame-shaped electrode and the second frame-shaped electrode; wherein

each of the first frame-shaped electrode, the second frame-shaped electrode, and the solder sealing frame includes a strip-shaped portion extending in the x direction and a strip-shaped portion extending in the y direction;

the element and the substrate are bonded together with the solder sealing frame, the functional part provided on the element is hermetically sealed in a space formed between the element and the substrate; and

when the difference in expansion in the x direction between the element and the substrate is represented by Q_x and the difference in expansion in the y direction between the element and the substrate is represented by Q_y , in each of the first frame-shaped electrode, the second frame-shaped electrode, and the solder sealing frame, a

width of the strip-shaped portion extending in the direction having the larger difference in expansion is smaller than a width of the strip-shaped portion extending in the direction having the smaller difference in expansion.

Claim 7 (previously presented): The electronic component device according to claim 6, wherein the thickness of the solder sealing frame is about 18 μm or more.

Claim 8 (previously presented): The electronic component device according to claim 6, wherein when the coefficient of linear expansion in the x direction of the substrate is represented by A_x , the coefficient of linear expansion in the y direction of the substrate is represented by A_y , the coefficient of linear expansion in the x direction of the element is represented by B_x , the coefficient of linear expansion in the y direction of the element is represented by B_y , the length of the external side of the strip-shaped portion extending in the x direction of the first and second frame-shaped electrodes is represented by dl_x , the length of the external side of the strip-shaped portion extending in the y direction of the first and second frame-shaped electrodes is represented by dl_y , the difference Q_x in expansion is represented by $Q_x = |A_x - B_x| \times dl_x$ (mm/ $^{\circ}\text{C}$), and the difference Q_y in expansion is represented by $Q_y = |A_y - B_y| \times dl_y$ (mm/ $^{\circ}\text{C}$), then the larger difference in expansion is about 2.2×10^{-5} (mm/ $^{\circ}\text{C}$) or less.

Claim 9 (previously presented): The electronic component device according to claim 6, wherein when the ratio of flexural rigidity in the x direction between the element and the substrate is represented by R_x and the ratio of flexural rigidity in the y direction between the element and the substrate is represented by R_y , the larger ratio of the flexural rigidity ratios R_x and R_y is about 1.2 or less.

Claim 10 (previously presented): The electronic component device according to claim 6, wherein the element is a surface acoustic wave element.

Claim 11 (previously presented): The electronic component device according to claim 6, wherein the element is a high frequency element.

Claim 12 (previously presented): An electronic component device comprising:
a rectangular plate-shaped element including a functional part and a first frame-shaped electrode, wherein the coefficient of linear expansion in the x direction along a side of the rectangle is different from the coefficient of linear expansion in the y direction orthogonal to the x direction in the rectangular plane; and

a substrate including a second frame-shaped electrode; wherein
each of the first frame-shaped electrode and the second frame-shaped electrode includes a strip-shaped portion extending in the x direction and a strip-shaped portion extending in the y direction;

the element and the substrate are bonded together with the functional part provided on the element hermetically sealed in a space formed between the element and the substrate; and

when the difference in expansion in the x direction between the element and the substrate is represented by Q_x and the difference in expansion in the y direction between the element and the substrate is represented by Q_y , in each of the first frame-shaped electrode and the second frame-shaped electrode, a width of the strip-shaped portion extending in the direction having the larger difference in expansion is smaller than a width of the strip-shaped portion extending in the direction having the smaller difference in expansion.